

FSP-501

- FSP 501是Micro Thin底层树脂涂层的SAP材料。
FSP501 is SAP(Semi Additive Process) material which is coated primer resin on Micro Thin.
- 适用于线宽/线距(L/ S) =20/20或以下之应用。
Usable for fine pitch pattern L/S=20/20 or less formation.

用途/Application

- IC封装基板
/Semiconductor Package

构成/Composition



生产地点/Production Site

- 日本 / Japan

代表性特性数据/Representative data

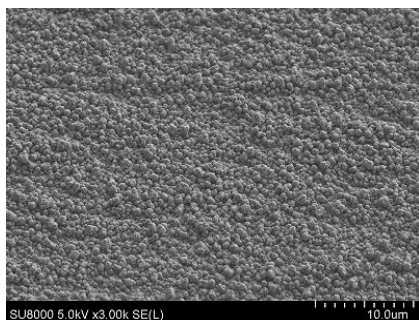
	μm	Area weight (w/o Primer) (g/m ²)	Laminate side Rz(μm)	Tensile Strength (N/mm ²)	Elongation (%)	Peel Strength (kg/cm) ^{@FR-4}
FSP501	1.5	18	1.4	-	-	-
	2	21	1.4	-	-	-
	3	30	1.4	-	-	-

※上述表列为代表性数据非保证值
This is representative data, not guaranteed.

※Peel Strength为增镀到35 μm 厚度之后的测试值
Evaluated after plated up to 35 μm .

底层树脂涂层涂工前处理面/

Laminate side before Primer coat



阻剂面/ resist side

